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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/663,898	09/16/2003	Aron T. Lunde	2269-5457US (01-1366.00/U)	4518
24247	7590	05/03/2005		EXAMINER
TRASK BRITT P.O. BOX 2550 SALT LAKE CITY, UT 84110			NGUYEN, DILINH P	
			ART UNIT	PAPER NUMBER
			2814	

DATE MAILED: 05/03/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No.	Applicant(s)	
	10/663,898	LUNDE ET AL.	
	Examiner DiLinh Nguyen	Art Unit 2814	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 07 February 2005.

2a) This action is FINAL. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1-22 is/are pending in the application.

4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5) Claim(s) _____ is/are allowed.

6) Claim(s) 1-22 is/are rejected.

7) Claim(s) _____ is/are objected to.

8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some * c) None of:

- Certified copies of the priority documents have been received.
- Certified copies of the priority documents have been received in Application No. _____.
- Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892)

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____.

4) Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.

5) Notice of Informal Patent Application (PTO-152)

6) Other: _____.

DETAILED ACTION

Response to Amendment

1. The amendment filed 2/7/2005 is objected to under 35 U.S.C. 132(a) because it introduces new matter into the disclosure. 35 U.S.C. 132(a) states that no amendment shall introduce new matter into the disclosure of the invention. The added material which is not supported by the original disclosure is as follows: the at least a second functional die formed and coupled as a unitary integral wafer segment with the first functional die.

Applicant is required to cancel the new matter in the reply to this Office Action.

Claim Rejections - 35 USC § 112

2. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.
3. Claims 1-22 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

The at least a second functional die formed and coupled as a unitary integral wafer segment with the first functional die (claim 1); the at least one nonfunctional die being formed on the unitary integral wafer segment (claims 6, 12 and 20); the two or more functional dice being on a unitary integral wafer segment (claim 9); and the first

and second functional dice being on a unitary integral portion of the semiconductor wafer and further configured as an independently functional segment of the semiconductor wafer (fig. 15) are new subject matter.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

5. Claims 1-4, 9, 11 and 13 are rejected under 35 U.S.C. 102(e) as being anticipated by Kim (U.S. Pat. 6,486,005).

Kim discloses a semiconductor device comprising:

a first functional die 31a including at least a first bond pad 32;
at least a second functional die 31b including at least a second bond pad 32; and
an adjacent die interconnection circuit 38 operably coupling the at least the first bond pad of the first functional die with the at least the second bond pad of the at least the second functional die (fig. 3G, column 3, lines 47 et seq.).

- Regarding claim 2, Kim discloses that the adjacent die interconnection circuit includes at least one conductor segment 38 having a first end electrically coupled to the at least the first bond pad and a second end electrically coupled to the at least the second bond pad (fig. 3G).

- Regarding claim 3, Kim discloses that the adjacent die interconnection circuit further includes a conductive bump 40 electrically coupled to the at least one conductor segment configured for operatively coupling the at least one conductor segment of the semiconductor device with the substrate contact of a high level packaging element (fig. 3G).
- Regarding claim 4, Kim discloses that the first functional die and the second functional die are immediately adjacent (fig. 3G).
- Regarding claim 9, Kim discloses a segment of a semiconductor wafer, comprising: two functional dice 31a and 31b each including at least one bond pad 32; and an adjacent die interconnection circuit 38 for mutually operably coupling each at least one bond pad of the two functional dice to at least one other bond pad 32 of the two functional dice (fig. 3G, column 3, lines 47 et seq.).
- Regarding claim 11, Kim discloses that the adjacent die interconnection circuit includes at least one conductor segment 38 for coupling between each of the two functional dice, the conductor segment including a first end electrically coupled to the at least one bond pad on one of the two functional dice and a second end electrically coupled to the at least one bond pad on another of the two functional dice (fig. 3G).
- Regarding claim 13, Kim discloses that the two functional dice are immediately adjacent on the segment of semiconductor wafer (fig. 3G).

Claim Rejections - 35 USC § 103

6. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

7. Claims 5, 10, 14-19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kim (U.S. Pat. 6,486,005) in view of Farnworth et al. (U.S. Pat. 6,744,067).

- Regarding claims 5, 10, 14-15, Kim substantially discloses all the limitations as claimed above except for the first functional die and the second functional die are separated by at least one nonfunctional die.

However, Farnworth et al. disclose that a first functional die and a second functional die are separated by at least one nonfunctional die (column 3, lines 28-30). Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to test the device structure of Kim by having the nonfunctional die between the first and second functional dice, as taught by Farnworth et al., for testing of each individual die or groups of dice in order to determine and segregate operational dice from nonfunctional die (column 8, lines 25-28).

- Regarding claim 16, Kim discloses that the first functional die and the second functional die are immediately adjacent on the semiconductor wafer (fig. 3G).
- Regarding claim 17, Farnworth et al. discloses that the first functional die and the second functional die are separated by at least one nonfunctional die on the semiconductor wafer (column 3, lines 28-31).

- Regarding claim 18, Kim discloses that the adjacent die interconnection circuit includes at least one conductor segment 38 having a first end electrically coupled to the first bond pad and a second end electrically coupled to the second bond pad for electrically coupling the first bond pad with the second bond pad (fig. 3G).
- Regarding claim 19, Kim discloses that the adjacent die interconnection circuit further includes a conductive bump 40 electrically coupled to the at least one conductor segment configured for operatively coupling the at least one conductor segment of the semiconductor wafer with a contact of a higher level packaging (fig. 3G).

Response to Arguments

Applicant's arguments filed 2/7/05 have been fully considered but they are not persuasive.

- The applicant argues that Kim does not disclose the at least a second functional die formed and coupled as a unitary integral wafer segment with the first functional die.

Applicant's argument have been fully considered but they are not persuasive because the newly added limitation, such as: at least a second functional die formed and coupled as a unitary integral wafer segment with the first functional die is new subject matter. Neither the drawings nor the specification discloses this new subject matter.

- In response to applicant's argument that there is no suggestion or no motivation to combine the references. However, the obviousness can only be established

by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one of ordinary skill in the art. See *In re Fine*, 837 F.2d 1071, 5 USPQ2d 1596 (Fed. Cir. 1988) and *In re Jones*, 958 F.2d 347, 21 USPQ2d 1941 (Fed. Cir. 1992). In this case, Farnworth et al. disclose that a first functional die and a second functional die are separated by at least one nonfunctional die (column 3, lines 28-30). It would have been obvious to one having ordinary skill in the art at the time the invention was made to test the device structure of Kim by having the nonfunctional die between the first and second functional dice, as taught by Farnworth et al., for testing of each individual die or groups of dice in order to determine and segregate operational dice from nonfunctional die (column 8, lines 25-28). Therefore, the teaching or suggestion to make the claimed combination and the reasonable expectation of success had been found in Farnworth et al. (column 8, lines 25-28), and not based on applicant's disclosure.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (571) 272-1712. The examiner can normally be reached on 8:00AM - 6:00PM (M-F).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

DLN



Hoai Pham

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PRIMARY EXAMINER